

QT-Brightek Chip LED Series

0402 SMD Green LED

Part No.: QBLP595-2IG-2897

2897: High Brightness Version

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Introduction

Feature:

- Water clear lens
- Package in tape and reel
- Color: green
- Compact 0402 package
- InGaN technology
- Viewing angle: 140° typ.
- Height profile: 0.5mm

Application:

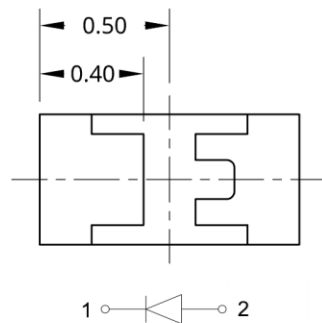
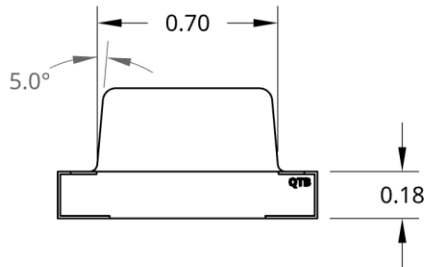
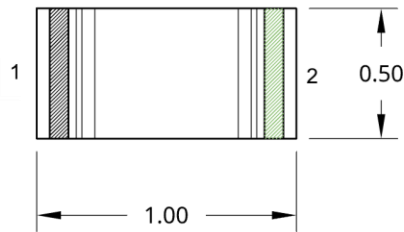
- Status indication
- Back lighting application

Certification & Compliance:

- ISO9001
- RoHS Compliant



Dimension:



Units: mm / tolerance = +/-0.1mm

Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	I _F (mA)	V _F (V)		λ _D (nm)			λ _P (nm)	I _V (mcd)	
			Typ.	Max.	Min.	Typ.	Max.	Typ.	Min.	Typ.
QBLP595-2IG-2897	Green	20	3.1	3.7	520	525	530	515	450	850

Absolute Maximum Rating

Chip Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SO L} (°C)**
InGaN	93	30	100	5	-40 ~ +80	-40 ~ +85	260

*Duty 1/10 @ 1KHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F @ I_F=20mA

Bin	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

Luminous Intensity I_V @ I_F=20mA

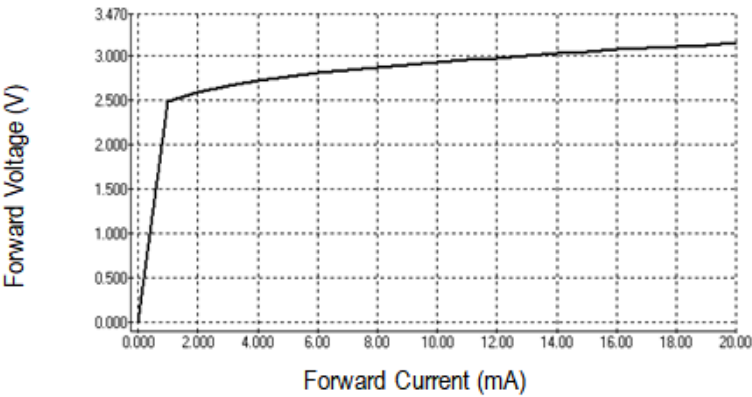
Bin	Min.	Max.	Unit
1B	450	565	mcd
2B	565	706	
3B	706	883	
4B	883	1104	
5B	1104	1380	

Dominant Wavelength λ_D @ I_F=20mA

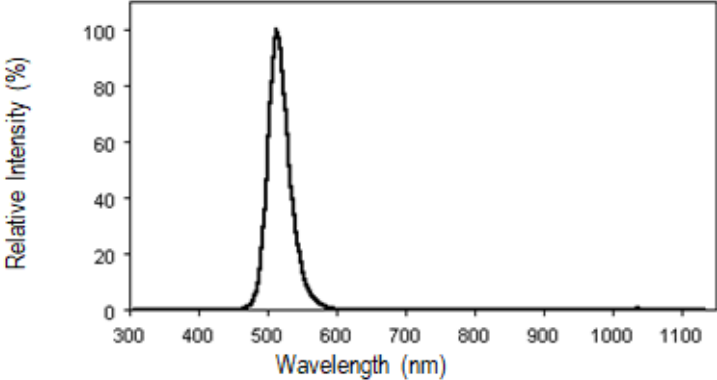
Bin	Min.	Max.	Unit
U	520	522.5	nm
V	522.5	525	
W	525	527.5	
X	527.5	530	

Characteristic Curves

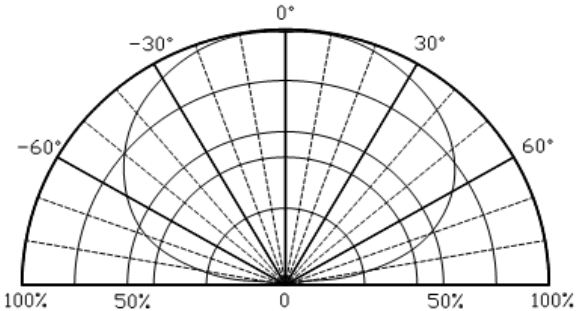
Forward Current vs. Forward Voltage



Relative Intensity vs. Wavelength

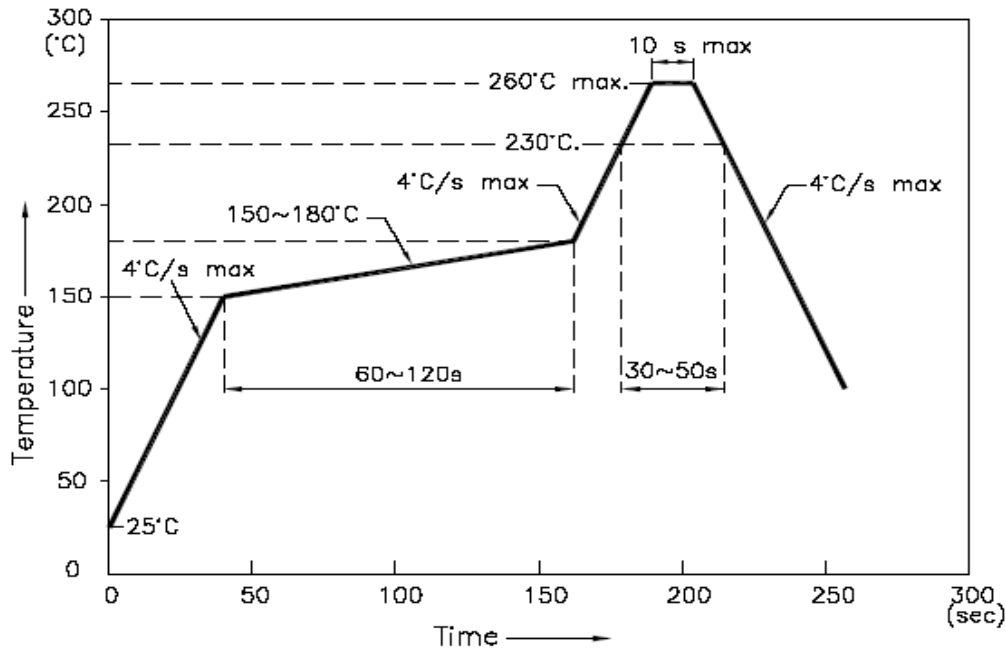


Directive Characteristics

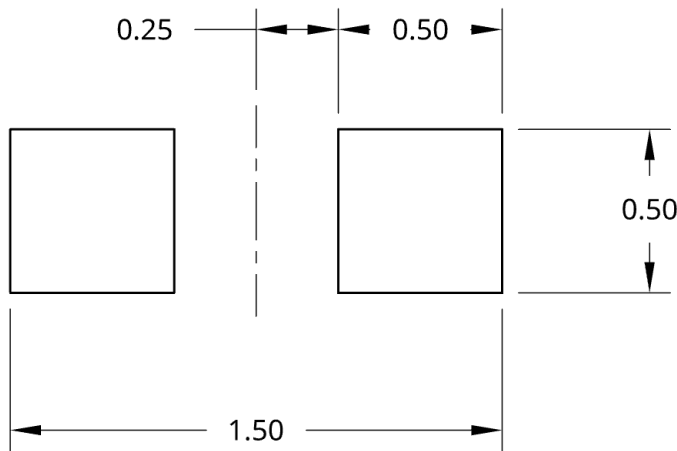


Solder Profile & Footprint

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



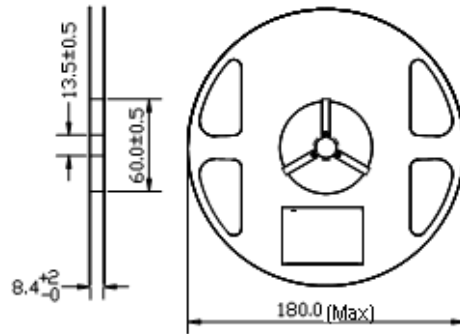
Recommended Pad Layout



Units: mm

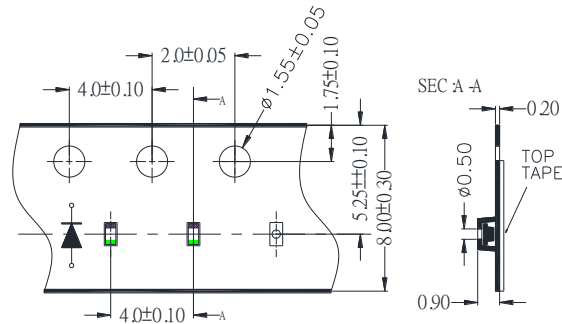
Packing

Reel Dimension:



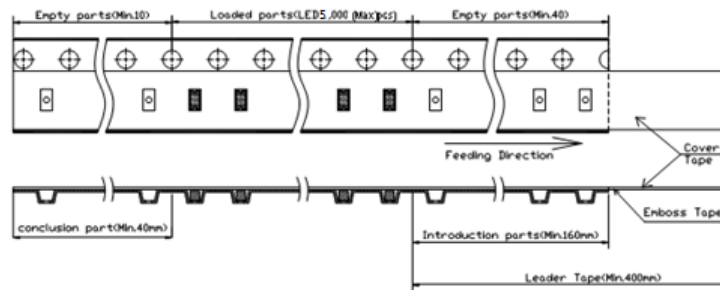
(Unit: mm)

Tape Dimension:

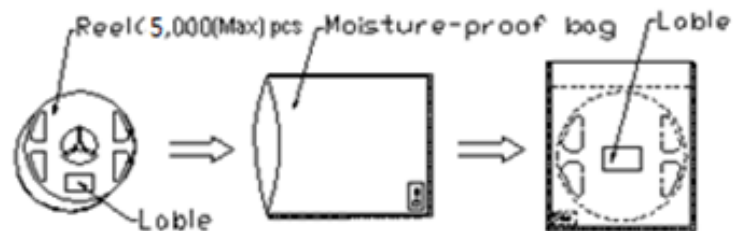


(Unit: mm)

Arrangement of Tape:



Packaging Specifications:





Revision History

Description:	Revision #	Revision Date
New Release of QBLP595-2IG5-2897	V1.0	04/11/2025
Drawing redrafted for clarity and documentation consistency; no changes to form, fit, or function.	V1.2	02/13/2026

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- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.